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PATENT APPLICATION TRANSMITTAL LETTER

(Large Entity)

Docket No. 36080.00800

Edward G. COMBS, et al.

For:	Enhanced Thermal Dissipation Integrated Circuit Package and Method of Manufacturing Enhanced Thermal

Dissipation	Integrated	Circuit	Package
Carles and areas			

Enclo	sed	are:
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- ☑ Certificate of Mailing with Express Mail Mailing Label No. EL 819 057 922US
- ☐ A certified copy of a

application.

☑ Declaration

- Power of Attorney
- Information Disclosure Statement
- Preliminary Amendment
- Other: 19 pp. Disclosure (12 pg. Specification, 6 pg. claims, 1 pp. Abstract)

CLAIMS AS FILED

For	#Filed	#Allowed	#Extra		Rate	Fee
Total Claims	26	- 20 =	6	х	\$18.00	\$108.00
្សា Indep. Claims	6	- 3 =	3	х	\$80.00	\$240.00
Multiple Dependent C	laims (check	if applicable)				\$0.00
The state of the s					BASIC FEE	\$710.00
The state of the s					TOTAL FILING FEE	\$1,058.00

- A check in the amount of
- \$1,058.00

to cover the filing fee is enclosed.

The Commissioner is hereby authorized to charge and credit Deposit Account No.

13-5200

as described below. A duplicate copy of this sheet is enclosed.

- ☐ Charge the amount of
- as filing fee.
- ☑ Credit any overpayment.
- ☐ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.
- ☐ Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

Dated: July 11, 2001

Signature

Christopher J. Gaspar, Registration No. 41,030 MILBANK, TWEED, HADLEY & McCLOY LLP

One Chase Manhattan Plaza New York, New York 10005 Telephone (212)530-5019 Facsimile (212)822-5019

CC:

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Docket No. 36080.00800

Total Pages in this Submission

4

TO THE ASSISTANT COMMISSIONER FOR PATENTS

Box Patent Application Washington, D.C. 20231

Washington, D.C. 20231
ransmitted herewith for filing under 35 U.S.C. 111(a) and 37 C.F.R. 1.53(b) is a new utility patent application for an
nvention entitled: ENHANCED THERMAL DISSIPATION INTEGRATED CIRCUIT PACKAGE AND METHOD OF
MANUFACTURING ENHANCED THERMAL DISSIPATION INTEGRATED CIRCUIT PACKAGE
and invented by:
Edward G. COMBS, 290 Killdeer Ct., Foster, CA 94404; Robert P. SHEPPARD, 1215 Washington St., Red Bluff, CA 96080; Tai Wai PUN, Flat H 29/F, Maywood Ct., Kingswood Villas, Tin Shui Wai, N.T., HK; Hau Wan NG, Rm. 1526,
Oi Shun Hse., Yau Oi Est., Tuen Mun, HK; Chun Ho FAN, Flat E, 27/F, Block 3, Lido Garden, Sham Tseng, HK; and
Neil R. MCLELLAN, #3 Tregunter Path Flat 3B, Mid Levels, HK.
a CONTINUATION APPLICATION, check appropriate box and supply the requisite information:
Continuation Divisional Continuation-in-part (CIP) of prior application No.:
Which is a:
Continuation Divisional Continuation-in-part (CIP) of prior application No.:
Which is a: Continuation Divisional Continuation-in-part (CIP) of prior application No.:
Continuation Divisional Continuation-in part (cir.) Continuation Continua
Enclosed are:
Application Elements
1. 🗵 Filing fee as calculated and transmitted as described below
2. Specification having pages and including the following:
a. 🗵 Descriptive Title of the Invention
b. ☐ Cross References to Related Applications (if applicable)
c. Statement Regarding Federally-sponsored Research/Development (if applicable)
d. Reference to Microfiche Appendix (if applicable)
e. 🗵 Background of the Invention
f. 🗵 Brief Summary of the Invention
g. Brief Description of the Drawings (if drawings filed)
h. 🗵 Detailed Description
i. ⊠ Claim(s) as Classified Below
j. 🗵 Abstract of the Disclosure

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Docket No. 36080.00800

Total Pages in this Submission

4

Application Elements (Continued) Drawing(s) (when necessary as prescribed by 35 USC 113) 3. Number of Sheets Formal a. 🔲 11 (Figs. 1-11) Number of Sheets Informal \boxtimes Oath or Declaration \times Newly executed (original or copy) Unexecuted a. 🖾 Copy from a prior application (37 CFR 1.63(d)) (for continuation/divisional application only) b. 🗆 Without Power of Attorney With Power of Attorney c. 🗵 DELETION OF INVENTOR(S) d. 🗆 Signed statement attached deleting inventor(s) named in the prior application, see 37 C.F.R. 1.63(d)(2) and 1.33(b). ☐ Incorporation By Reference (usable if Box 4b is checked) Ū The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4b, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein. H ☐ Computer Program in Microfiche (Appendix) ☐ Nucleotide and/or Amino Acid Sequence Submission (if applicable, all must be included) a. 🔲 Paper Copy Computer Readable Copy (identical to computer copy) b. 🗆 Statement Verifying Identical Paper and Computer Readable Copy c. 🔲 **Accompanying Application Parts** ☐ Assignment Papers (cover sheet & document(s)) ☐ 37 CFR 3.73(B) Statement (when there is an assignee) 10. ☐ English Translation Document (if applicable) ☑ Information Disclosure Statement/PTO-1449 Preliminary Amendment 13. Acknowledgment postcard Certificate of Mailing 14. \mathbf{X} Express Mail (Specify Label No.): EL 819 057 922US First Class

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Docket No. 36080.00800

Total Pages in this Submission

Accompanying Application Parts (Continued)

	Accompanying Application Parts (Continued)
15.	Certified Copy of Priority Document(s) (if foreign priority is claimed)
16.	Additional Enclosures (please identify below):
	Request That Application Not Be Published Pursuant To 35 U.S.C. 122(b)(2)
7.	Pursuant to 35 U.S.C. 122(b)(2), Applicant hereby requests that this patent application not be published pursuant to 35 U.S.C. 122(b)(1). Applicant hereby certifies that the invention disclosed in this application has not and will not be the subject of an application filed in another country, or under a multilateral international agreement, that requires publication of applications 18 months after filing of the application.
	Warning
	An applicant who makes a request not to publish, but who subsequently files in a foreign country or under a multilateral international agreement specified in 35 U.S.C. 122(b)(2)(B)(i), must notify the Director of such filing not later than 45 days after the date of the filing of such foreign or international application. A failure of the applicant to provide such notice within the prescribed period shall result in the application being regarded as abandoned, unless it is shown to the satisfaction of the Director that the delay in submitting the notice was unintentional.

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Docket No. 36080.00800

Total Pages in this Submission

Fee Calculation and Transmittal

4.5 3		CLAIMS	AS FILED			
For	#Filed	#Allowed	#Extra		Rate	Fee
For otal Claims	26	-20 =	6	x	\$18.00	\$108.00
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ultiple Dependent Cla	ims (check	if applicable)				\$0.00
				•	BASIC FEE	\$710.00
OTHER FEE (specify	ourpose)					\$0.00
Total Control	<u>-</u> -				TOTAL FILING FEE	\$1,058.00
	verpayment.					
☐ Charge the	additional fil		3 at the mailir — Ci M	g of the	and 1.17. Notice of Allowance, Signature or J. Gaspar, Registration Notweed, Hadley & McCloy, L. Manhattan Plaza	

CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)

Docket No. 36080-00800

Applicant:

Ed Combs et al. To Be Assigned

Serial No.: Date Filed:

July 11, 2001 (Herewith)

Group Art Unit: To Be Assigned

For:

ENHANCED THERMAL DISSIPATION INTEGRATED CIRCUIT

PACKAGE AND METHOD OF MANUFACTURING ENHANCED THERMAL DISSIPATION INTEGRATED CIRCUIT PACKAGE

I hereby certify that this:

Certificate of Mailing by Express Mail (Label No. EL 819 057 922US); Patent Application Transmittal Letter (Large Entity); Utility Patent Application Transmittal (Large Entity); Utility Patent Application consisting of 12 pages of specification, 6 pages of claims, 1 page of Abstract and 11 sheets of formal drawings (Figs. 1-11); Declaration and Power of Attorney (4 pages); check in the amount of \$1,054 to cover application fee; and acknowledgment postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: The Commissioner for Patents, Box New Patent Applications, Washington, D.C. 20231 on:

July 11, 2001

Sandina M. Marino

Typed Name of Person Mailing Correspondence

Signature of Person Mailing Correspondence

EL 819 057 922US

("Express Mail" Mailing Label Number)